

Strontium Ruthenate



Sputtering Targets



Kurt J. Lesker[®]
Company

MATERIALS[™]
DIVISION

Applications

- Non-volatile Memory/FRAM
- Thin film capacitors
- Ferroelectric

Features

- High purity
- Custom Sizes Available

Process

- Manufacturing
 - Cold pressed
 - Sintered
 - Indium bonded to backing plate
- Cleaning and final packaging
 - Cleaned for use in vacuum
 - Protection from environmental contaminants
 - Protection during shipment

Options

- 99.9% minimum purity
- Up to 12.0" Diameter Targets Available
- Planar Tiles Up to 8" X 5" for Larger Target Configurations

www.lesker.com

Specifications

Typical Analysis - 99.9% (3N) Purity

Metallic Impurities, ppm by weight

Au	Ba	Ca	Cl	Fe	Ir	Mg	Na	Ni	Os	Pd
<5	<250	<100	<20	<20	<10	<5	<10	<10	<5	<10

Pt	Rh	S	Si
<10	<10	<5	<5

Theoretical Density	4.5 g/cc
Typical Density	4.00 g/cc
Appearance	White/Yellow/Beige
Particle Size	D50

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